

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
ZVI OR-BACH	04/04/2021
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	MONOLITHIC 3D INC.
<b>Street Address:</b>	1662 COVE POINT RD
<b>City:</b>	KLAMATH FALLS
<b>State/Country:</b>	OREGON
<b>Postal Code:</b>	97601
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17222784
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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<b>ATTORNEY DOCKET NUMBER:</b>	MONOLITHIC3D-ZENO2CON6
<b>NAME OF SUBMITTER:</b>	BRIAN CRONQUIST
<b>SIGNATURE:</b>	/Brian Cronquist/
<b>DATE SIGNED:</b>	04/05/2021
<b>Total Attachments: 1</b>	
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**ASSIGNMENT**

Whereas, I, **Zvi Or-Bach (hereinafter referred to as Assignor(s)), residing in Haifa, Israel;** have made a certain invention, and executed United States Patent Application entitled:

**A 3D SEMICONDUCTOR DEVICE AND STRUCTURE WITH MEMORY**

as described in U.S. Patent Application Serial No. 17/tbd and filed on April 4<sup>th</sup> or 5<sup>th</sup>, 2021; and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601 US (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

**INVENTOR:**

**DATE** on 04 / 04 / 2021

(**Zvi**

First Name

Middle Initial

**Or-Bach)**

Last Name

*72-1/12 '23*